Product Change Notification

107812 – 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #:	**107812 – 00**
Change Title:	**Introduction of Second and Third Assembly Locations for Intel® Demodulator Products: CE6313, CE6210, CE6354 and, CE6355, PCN 107812-00, Product Marking and Additional Assembly Sites**
Date of Publication:	**August 22, 2007**

Key Characteristics of the Change:

Product Marking
Manufacturing Site

Forecasted Key Milestones:

Addition of assembly location StatsChippac Singapore begins:	Nov 20, 2007
Addition of assembly location StatsChippac China begins:	Mar 31, 2008

Description of Change to the Customer:

In order to meet demand, ensure continuity of supply and remain competitive on cost, Intel is announcing the addition of a second and third assembly location for the products detailed below.

Customer Impact of Change and Recommended Action:

There is no change to form, fit or function of the affected parts. Assembly location will be identifiable by the country of origin.

Products Affected / Intel Ordering Codes:

Affected Product Code	**Affected S-Spec**	**Affected MM#**
WJCE6313		882207
WJCE6354	S L9G6	882208
WJCE6354		882209
WJCE6355		882210
WJCE6355		882211
WJCE6355	S L9G7	882212
WJCE6210		882214

Reference Documents / Attachments:

Document:	**Location #:**

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
August 22, 2007	00	Originally Published PCN